

Technical Data Sheet

1.6mm Round Subminiature Side Looking Phototransistor

EAPSV3224A0

Features

- Fast response time
- High photo sensitivity
- Small junction capacitance
- Package in 8mm tape on 7" diameter reels.
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

• EAPSV3224A0 is a phototransistor in miniature SMD package which is molded in a black with spherical top view lens. The device is Spectrally matched to infrared emitting diode.

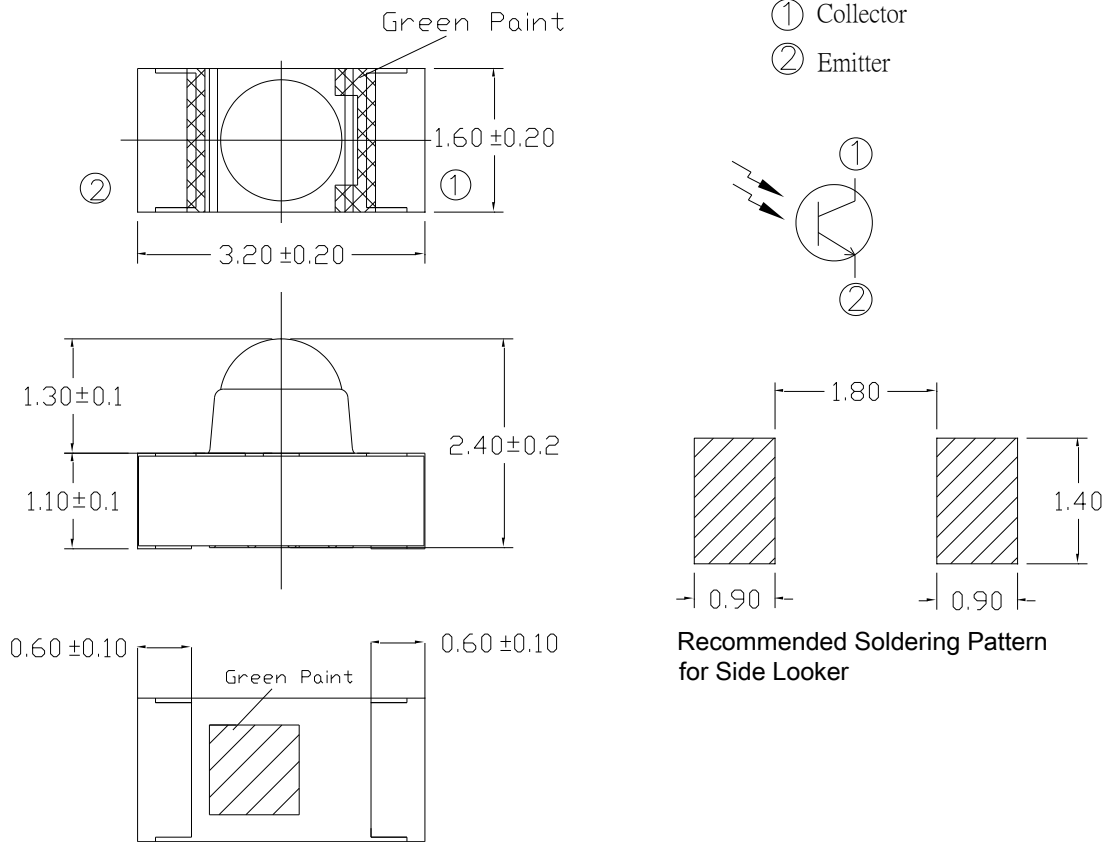
Applications

- Miniature switch
- Counters and sorter
- Position sensor
- Infrared applied system

Device Selection Guide

Device No.	Chip Material	Lens Color
EAPSV3224A0	Silicon	Black

Package Dimensions



- Notes:** 1.All dimensions are in millimeters
2.Tolerances unless dimensions ± 0.1 mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector-Voltage	V_{ECO}	5	V
Collector Current	I_C	20	mA
Operating Temperature	T_{opr}	-25 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Soldering Temperature *1	T_{sol}	260	°C
Power Dissipation at(or below) 25°C Free Air Temperature	P_c	75	mW

Notes: *1:Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

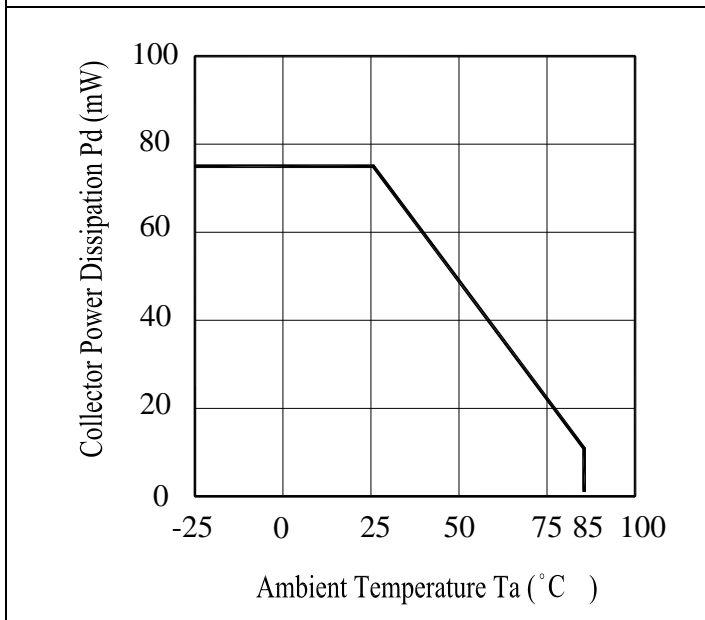
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Rang Of Spectral Bandwidth	$\lambda_{0.5}$	730	---	1100	nm	---
Wavelength Of Peak Sensitivity	λ_P	---	940	---	nm	---
Collector-Emitter Breakdown Voltage	BV_{CEO}	60	---	---	V	$I_C=500\mu A$ $E_e=0mW/cm^2$
Emitter-Collector Breakdown Voltage	BV_{ECO}	7	---	---	V	$I_E=50\mu A$ $E_e=0mW/cm^2$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	---	---	0.4	V	$I_C=5mA$ $E_e=1mW/cm^2$
Collector Dark Current	I_{CEO}	---	---	100	nA	$V_{CE}=20V$ $E_e=0mW/cm^2$
On State Collector Current	$I_{C(ON)}$	---	1.0	---	mA	$V_{CE}=5V$ $E_e=1mW/cm^2$ $\lambda_P=940nm$
Rise Time	t_r	---	15	---	μS	$V_{CE}=5V$ $I_C=1mA$ $R_L=1000\Omega$
Fall Time	t_f	---	15	---		

Rankings

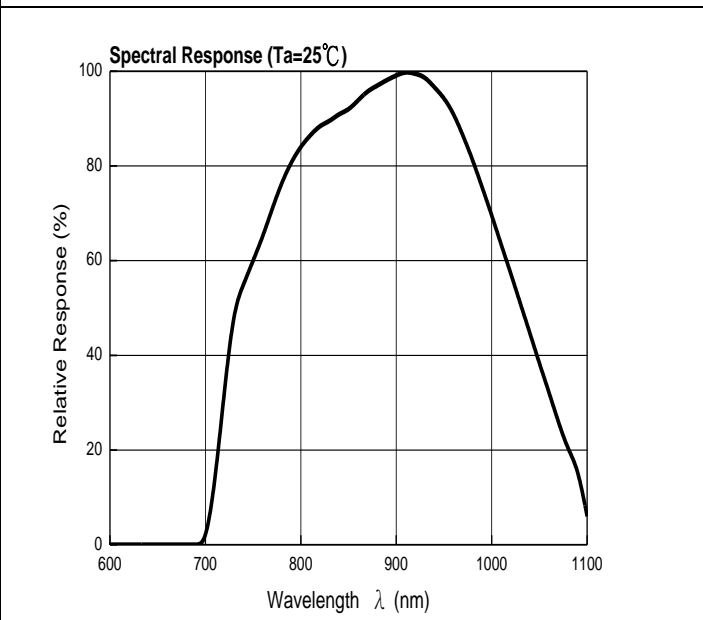
Rank	Symbol	Min	Max	Unit	Test Condition
BIN4	$I_{C(ON)}$	1.14	2.60	mA	$V_{CE}=5V$ $E_e=1mW/cm^2$ $\lambda_P=940nm$
BIN5		1.77	3.61		
BIN6		2.67	5.07		
BIN7		3.54	7.07		
BIN8		5.00	10.00		

Typical Electrical/Optical/Characteristics Curves

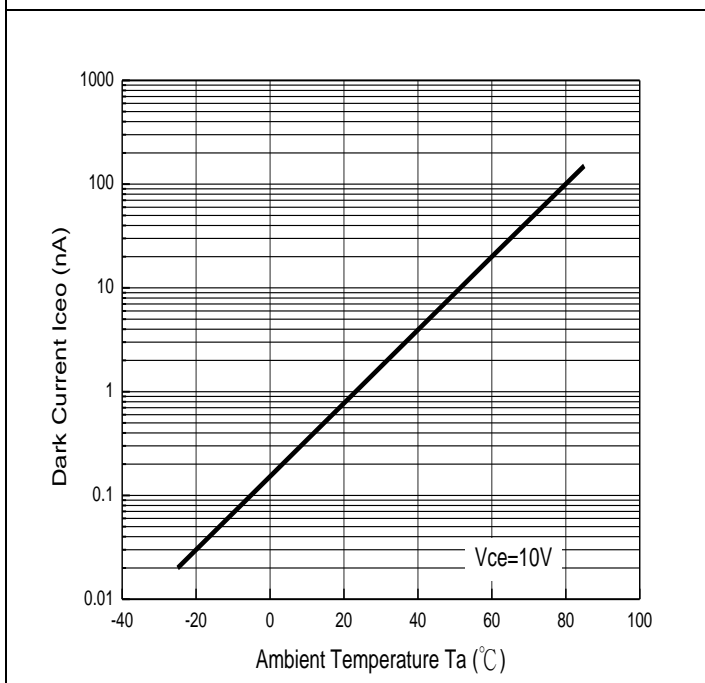
Collector Power Dissipation vs. Ambient Temperature



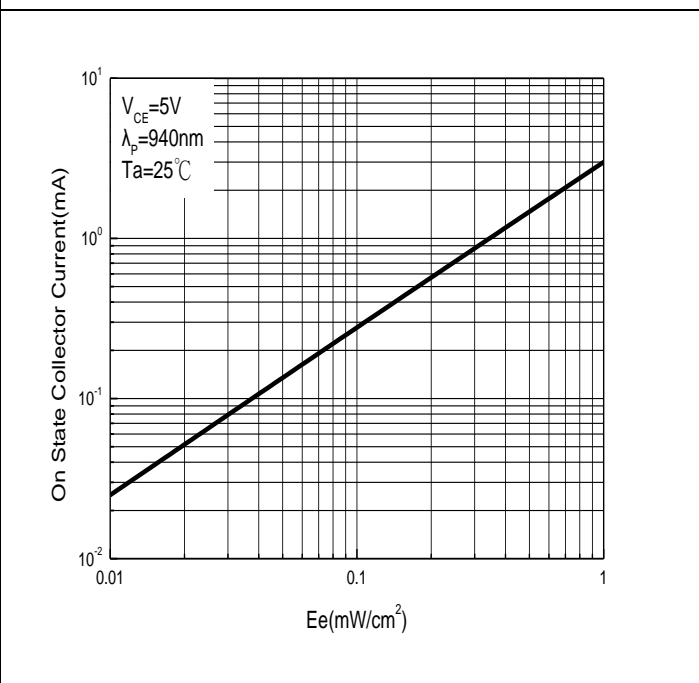
Spectral Sensitivity

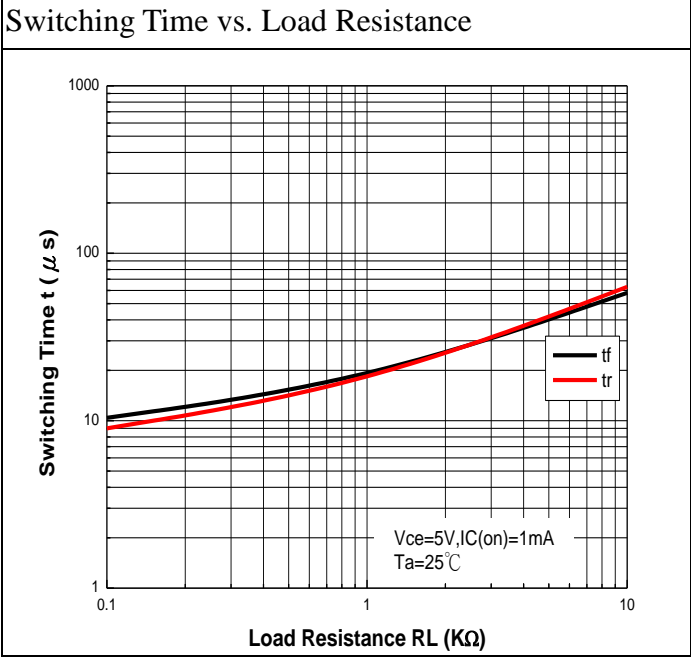


Collector Dark Current vs. Ambient Temperature



Collector Current vs. Irradiance





● **Precautions For Use**

1. Over-current-proof

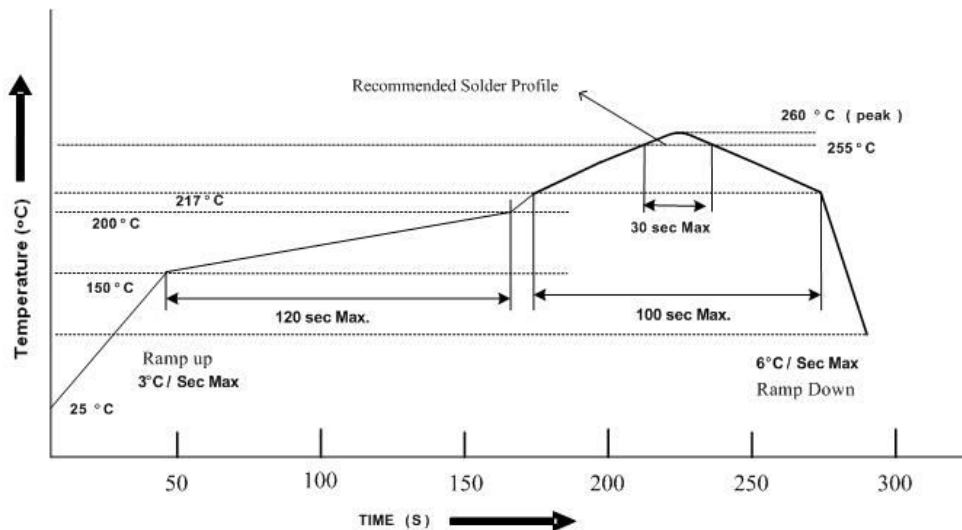
Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment : 60±5°C for Min 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



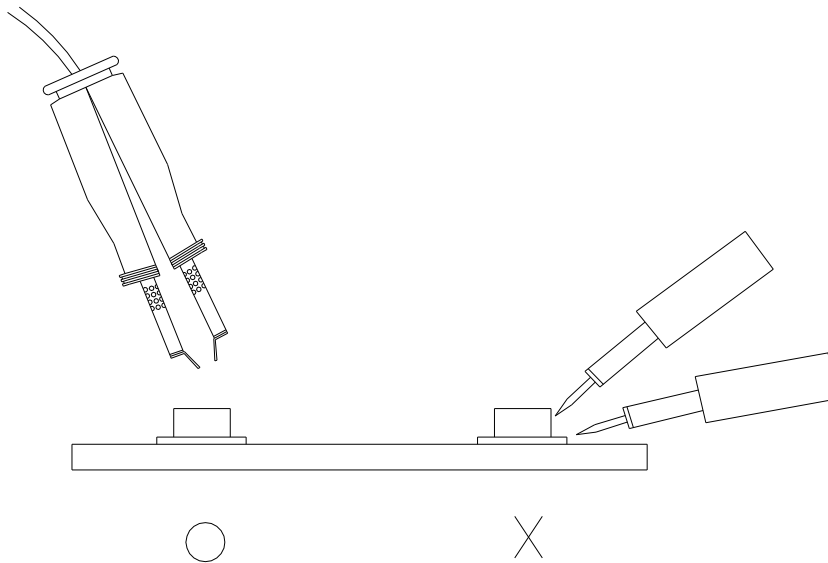
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

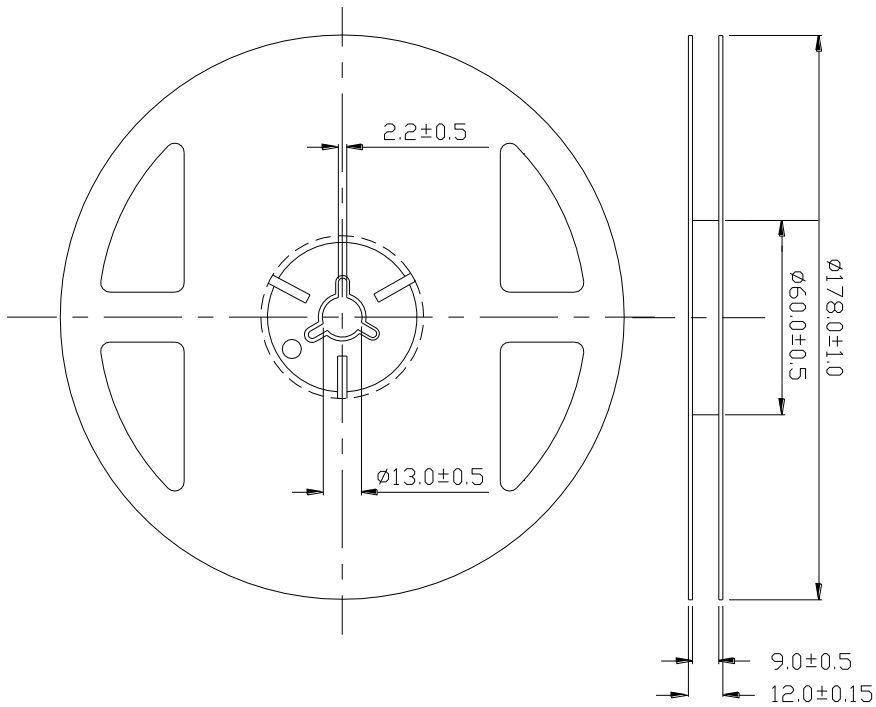
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

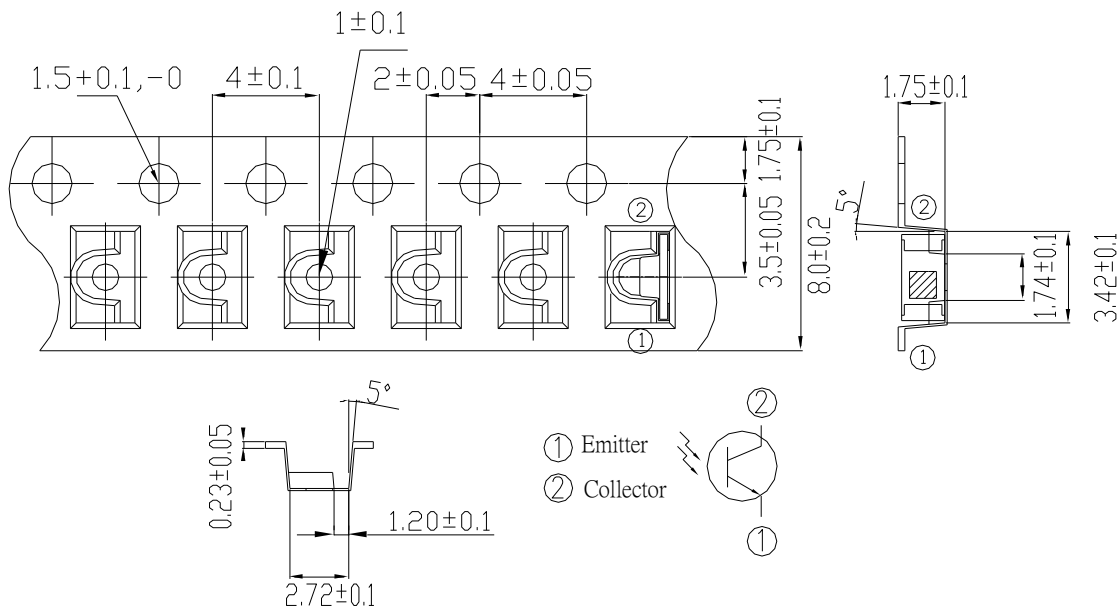


Package Dimensions



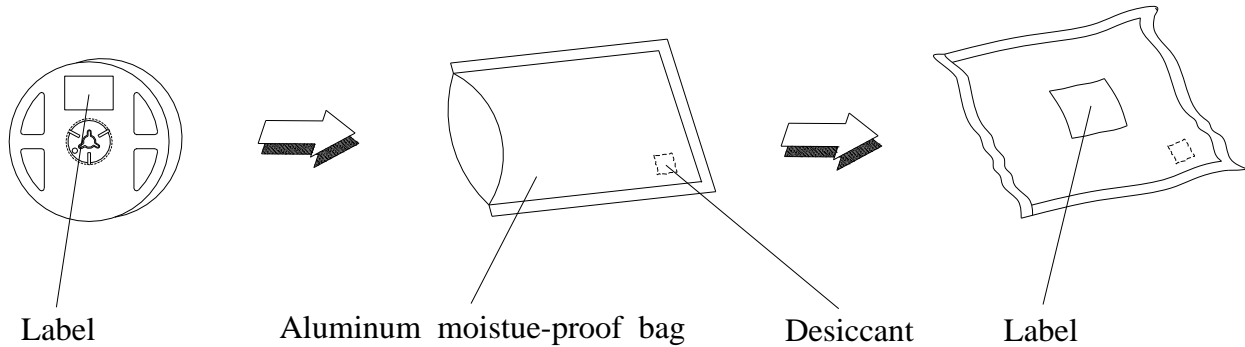
Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

2. Carrier Tape Dimensions:(Quantity: 1500pcs/reel)



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Packing Procedure



Label Form Specification

	EVERLIGHT AMERICA	
CPN: XXXXXXXXXXXX		
P/N: XXXXXXXXXXXX		
		RoHS
XXXXXXXXXXXXXXXXXXXX		
QTY: XXXX	CAT: XXX	
	HUE: XXX	
	REF: XXX	
LOT NO: XXXXXXXXXXXXXXXXXXXX		
REFERENCE: XXXXXXXXXXXX		
MADE IN TAIWAN		

CPN: Customer's Production Number
P/N : Production Number
QTY: Packing Quantity
CAT: Ranks
HUE: Peak Wavelength
REF: Reference
LOT No: Lot Number
MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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